

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): An epoxy resin composition for encapsulating semiconductors, comprising:

[(A)] an epoxy resin[.];

[(B)] a phenol resin[.];

[(C)] an inorganic filler[.];

[(D)] a curing accelerator[.];

[(E)] a glycerol tri-fatty acid ester produced by dehydration condensation reaction of glycerol and a saturated fatty acid with a carbon atom content of 24-36[.]; and

[(F)] a hydrotalcite compound,

wherein the inorganic filler is provided in an amount of 80-94wt% based on an overall weight of the epoxy resin composition, the glycerol tri-fatty acid ester is provided in an amount of 0.02-1 wt% based on the overall weight of the epoxy resin composition, and the hydrotalcite compound is provided in an amount of 0.01-5 wt% based on the overall weight of the epoxy resin composition, has an average particle diameter of 0.01-5 μm and has a specific surface area of 50 m^2/g or less.

Claim 2 (currently amended): The epoxy resin composition for encapsulating semiconductors according to claim 1, wherein the hydrotalcite compound is a compound ~~shown by the following~~ having a formula, $\text{Mg}_x\text{Al}_y(\text{OH})_z\text{CO}_3 \cdot n\text{H}_2\text{O}$, where x, y, z, and n are positive numbers, [(1)] and/or it's a sintered material of the compound having the formula, $\text{Mg}_x\text{Al}_y(\text{OH})_z\text{CO}_3 \cdot n\text{H}_2\text{O}$, where x, y, z, and n are positive numbers, $\text{Mg}_x\text{Al}_y(\text{OH})_z\text{CO}_3 \cdot n\text{H}_2\text{O}$ ~~(1) wherein x, y, z, and n are positive numbers or a combination of thereof.~~

Claim 3 (currently amended): The epoxy resin composition for encapsulating semiconductors according to claim 2, wherein the hydrotalcite compound is a hydrotalcite of

the ~~above~~ formula $[(1)]$ in which $0.15 \leq (y/x+y) \leq 0.35$, $1.8 \leq (z/x+y) \leq 2.5$, and $0 \leq n \leq 5$, ~~and/or it's a sintered material of the hydrotalcite of the formula in which~~ $0.15 \leq (y/x+y) \leq 0.35$, $1.8 \leq (z/x+y) \leq 2.5$, and $0 \leq n \leq 5$, or a combination thereof.

Claim 4 (currently amended): The epoxy resin composition for encapsulating semiconductors according to claim 1, wherein the hydrotalcite compound is a compound ~~shown by the~~ having a formula, $Mg_6Al_2(OH)_{16}CO_3 \cdot 4H_2O$.

Claim 5 (previously presented): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 1.

Claim 6 (previously presented): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 2.

Claim 7 (previously presented): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 3.

Claim 8 (previously presented): A semiconductor device comprising a semiconductor element encapsulated using the epoxy resin composition according to claim 4.